

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application: An-Chun Tu *et al.* : Group Art Unit: 2818
Serial Number: 10/700,779 : Examiner: David Nhu
Filed: 11/04/2003 : Attn. Docket No.: TS03-268
Title: METHOD FOR IMPROVING
INTERLEVEL DIELECTRIC GAP
FILLING OVER SEMICONDUCTOR : Date: July 13, 2004
STRUCTURES HAVING HIGH ASPECT
RATIOS

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AMENDMENT AND RESPONSE

Dear Sir:

This paper is responsive to the Office action dated May 26, 2004. Kindly enter the following amendments and remarks:



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PRINCETON, NJ 08540-6604
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A Delaware limited liability partnership
FRANK A. LUCHAK, RESIDENT PARTNER

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FACSIMILE TRANSMITTAL SHEET

TO: Art Unit 2818

FIRM/COMPANY: USPTO

FACSIMILE NUMBER: 703-872-9306

CONFIRMATION
TELEPHONE:

FROM: Won Joon Kouh

DIRECT DIAL: 609.919.4435

DATE: July 13, 2004

USER NUMBER: 3927

FILE NUMBER: USSN: 10/700,779

TOTAL # OF PAGES: 17
(INCLUDING COVERSHEET)

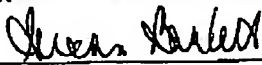
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| | | | |
|---|--------------------------|-----------------------|------------------------|
| CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8) | | | Docket No. TS03-268 |
| Applicant(s): An-Chun Tu et al. | | | |
| Application No. 10/700,779 | Filing Date 11/4/2003 | Examiner David Nhu | Group Art Unit 2818 |
| Invention: METHOD FOR IMPROVING INTERLEVEL DIELECTRIC GAP FILLING OVER SEMICONDUCTOR STRUCTURES HAVING HIGH ASPECT RATIOS | | | |
| <p>I hereby certify that this <u>Amendment and cover sheet</u> (Identify type of correspondence) is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-872-9306</u>) on <u>7/13/2004</u> (Date)</p> <p><u>Susan Barlett</u> (Typed or Printed Name of Person Signing Certificate)  (Signature)</p> <p>Note: Each paper must have its own certificate of mailing.</p> | | | |

P18REV02

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|--|-------------------------------------|-----------------------------|---|------------------------|--------------------------|--|---|--|--|
| AMENDMENT TRANSMITTAL LETTER (Large Entity) | | | | | Docket No. TS03-268 | | | | |
| Applicant(s): An-Chun Tu et al. | | | | | | | | | |
| Application No. 10/700,779 | Filing Date 11/4/2003 | Examiner David Nhu | Customer No. 28581 | Group Art Unit 2818 | Confirmation No. 5490 | | | | |
| Invention: METHOD FOR IMPROVING INTERLEVEL DIELECTRIC GAP FILLING OVER SEMICONDUCTOR STRUCTURES HAVING HIGH ASPECT RATIOS | | | | | | | | | |
| <u>COMMISSIONER FOR PATENTS:</u> | | | | | | | | | |
| Transmitted herewith is an amendment in the above-identified application. | | | | | | | | | |
| The fee has been calculated and is transmitted as shown below. | | | | | | | | | |
| CLAIMS AS AMENDED | | | | | | | | | |
| | CLAIMS REMAINING AFTER AMENDMENT | HIGHEST # PREV. PAID FOR | NUMBER EXTRA CLAIMS PRESENT | RATE | ADDITIONAL FEE | | | | |
| TOTAL CLAIMS | 26 - | 26 = | 0 x | \$18.00 | \$0.00 | | | | |
| INDEP. CLAIMS | 2 - | 3 = | 0 x | \$86.00 | \$0.00 | | | | |
| Multiple Dependent Claims (check if applicable) <input type="checkbox"/> | | | | | \$0.00 | | | | |
| TOTAL ADDITIONAL FEE FOR THIS AMENDMENT | | | | | \$0.00 | | | | |
| <input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-2061 <input type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input type="checkbox"/> Any patent application processing fees under 37 CFR 1.17. | | | | | | | | | |
|  Signature | | | Dated: 7/13/2004 | | | | | | |
| Won Joon Kouh, Esq. Reg. No. 42,763 Duane Morris LLP 100 College Road West, Suite 100 Princeton, NJ 08540 609-919-4435 | | | <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="padding: 5px;"> I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450. </td> </tr> <tr> <td style="height: 40px; text-align: center; vertical-align: middle;"> Signature of Person Mailing Correspondence </td> </tr> <tr> <td style="height: 40px; text-align: center; vertical-align: middle;"> Typed or Printed Name of Person Mailing Correspondence </td> </tr> </table> | | | | I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450. | Signature of Person Mailing Correspondence | Typed or Printed Name of Person Mailing Correspondence |
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